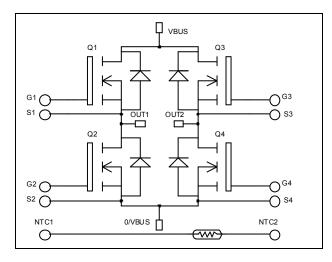


Full - Bridge MOSFET Power Module

$$\begin{split} V_{DSS} &= 200V \\ R_{DSon} &= 20 m \Omega \text{ typ @ Tj} = 25^{\circ} C \\ I_D &= 89 A \text{ @ Tc} = 25^{\circ} C \end{split}$$



G4 🛭

S4 [

S2 #

G2 f

O/VBUS

OUT2

OUT1

NTC2 #

NTC1 #

Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7[®] FREDFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Fast intrinsic reverse diode
 - Avalanche energy rated
 - Very rugged
 - Kelvin source for easy drive
- Very low stray inductance
- Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration



- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- RoHS Compliant

Absolute maximum ratings

Ø G3

8 S3

VBUS

| Symbol | Parameter | | Max ratings | Unit |
|--------------|---|---------------|-------------|------|
| $V_{ m DSS}$ | Drain - Source Voltage | | 200 | V |
| Ţ | Continuous Drain Current | $T_c = 25$ °C | 89 | |
| I_D | Continuous Diam Current | $T_c = 80$ °C | 66 | A |
| I_{DM} | Pulsed Drain current | | 356 | |
| V_{GS} | Gate - Source Voltage | | ±30 | V |
| R_{DSon} | Drain - Source ON Resistance | | 24 | mΩ |
| P_{D} | Maximum Power Dissipation $T_c = 25^{\circ}C$ | | 357 | W |
| I_{AR} | Avalanche current (repetitive and non repetitive) | | 89 | A |
| E_{AR} | Repetitive Avalanche Energy | | 50 | mJ |
| E_{AS} | Single Pulse Avalanche Energy | | 2500 | 1111 |

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

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All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

| Symbol | Characteristic | Test Conditions | Min | Typ | Max | Unit |
|------------------------------|----------------------------------|---|-----|-----|------|------|
| $\mathrm{BV}_{\mathrm{DSS}}$ | Drain - Source Breakdown Voltage | $V_{GS} = 0V, I_D = 250\mu A$ | 200 | | | V |
| T | Zero Gate Voltage Drain Current | $V_{GS} = 0V, V_{DS} = 200V$ $T_j = 25^{\circ}C$ | | | 250 | 4 |
| I_{DSS} | | $V_{GS} = 0V, V_{DS} = 160V$ $T_j = 125^{\circ}C$ | | | 1000 | μΑ |
| R _{DS(on)} | Drain – Source on Resistance | $V_{GS} = 10V, I_D = 44.5A$ | | 20 | 24 | mΩ |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS} = V_{DS}$, $I_D = 2.5 \text{mA}$ | 3 | | 5 | V |
| I_{GSS} | Gate – Source Leakage Current | $V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$ | | | ±100 | nA |

Dynamic Characteristics

| Symbol | Characteristic | Test Conditions | | Min | Тур | Max | Unit |
|------------------|------------------------------|--|----------------|-----|------|-----|------|
| C _{iss} | Input Capacitance | $V_{GS} = 0V$ $V_{DS} = 25V$ | | | 6850 | | |
| C_{oss} | Output Capacitance | | | | 2180 | | pF |
| C_{rss} | Reverse Transfer Capacitance | f = 1MHz | | 97 | | | |
| Q_{g} | Total gate Charge | $V_{GS} = 10V$ | | | 112 | | |
| Q_{gs} | Gate – Source Charge | $V_{\text{Bus}} = 100V$ | | | 43 | | nC |
| Q_{gd} | Gate – Drain Charge | $I_D = 75A$ | | 47 | | , | |
| $T_{d(on)}$ | Turn-on Delay Time | Inductive switching | g @ 125°C | | 28 | | |
| T_{r} | Rise Time | $V_{GS} = 15V$ | | 56 | | | |
| $T_{d(off)}$ | Turn-off Delay Time | $V_{\text{Bus}} = 133V$ $I_{\text{D}} = 75A$ | | | 81 | | ns |
| T_{f} | Fall Time | $R_G = 5\Omega$ | | 99 | | | |
| E_{off} | Turn-off Switching Energy | $V_{GS} = 15V$ $V_{Bus} = 133V$ | $T_j = 25$ °C | | 455 | | μJ |
| E_{off} | Turn-off Switching Energy | $I_D = 75A$ $R_G = 5\Omega$ | $T_j = 125$ °C | | 531 | | μJ |

Source - Drain diode ratings and characteristics

| Symbol | Characteristic | Test Conditions | | Min | Тур | Max | Unit |
|-------------------|--|-------------------------------------|--|-----|-------------|------------|------|
| I_S | Continuous Source current (Body diode) | | $Tc = 25^{\circ}C$ $Tc = 80^{\circ}C$ | | | 89 66 | A |
| V_{SD} | Diode Forward Voltage | $V_{GS} = 0V, I_S = -75A$ | <u> </u> | | | 1.3 | V |
| dv/dt | Peak Diode Recovery | | | | | 8 | V/ns |
| t_{rr} | Reverse Recovery Time | $I_S = -75A$ | $T_{j} = 25^{\circ}C$ $T_{j} = 125^{\circ}C$ | | | 220 420 | ns |
| Qrr | Reverse Recovery Charge | $V_R = 133V$ $di_S/dt = 100A/\mu s$ | $T_j = 25^{\circ}C$ $T_j = 125^{\circ}C$ | | 1.07 2.9 | | μС |

• dv/dt numbers reflect the limitations of the circuit rather than the device itself.

 $I_S \leq \text{- 75A} \qquad di/dt \leq 700 A/\mu s \qquad V_R \leq V_{DSS} \qquad T_j \leq 150^{\circ} C$



Thermal and package characteristics

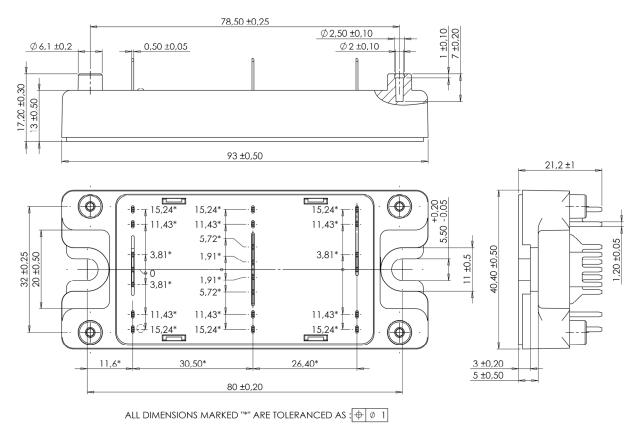
| Symbol | Characteristic | | Min | Max | Unit | |
|-------------|--|-------------|-----|------|------------------------|------|
| R_{thJC} | Junction to Case Thermal Resistance | | | | 0.35 | °C/W |
| V_{ISOL} | RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz | | | 4000 | | V |
| $T_{\rm J}$ | Operating junction temperature range | | | -40 | 150 | |
| T_{JOP} | Recommended junction temperature under switching conditions | | | -40 | T _J max -25 | °C |
| T_{STG} | Storage Temperature Range | | | -40 | 125 | |
| $T_{\rm C}$ | Operating Case Temperature | | | -40 | 100 | |
| Torque | Mounting torque | To Heatsink | M5 | 2.5 | 4.7 | N.m |
| Wt | Package Weight | | | 160 | g | |

| Symbol | Characteristic | Min | Тур | Max | Unit |
|------------------------|-----------------------------|-----|------|-----|------|
| R ₂₅ | Resistance @ 25°C | | 50 | | kΩ |
| $\Delta R_{25}/R_{25}$ | | | 5 | | % |
| $B_{25/85}$ | $T_{25} = 298.15 \text{ K}$ | | 3952 | | K |
| $\Delta B/B$ | T _C =100° | С | 4 | | % |

$$R_{T} = \frac{R_{25}}{\exp \left[B_{25/85} \left(\frac{1}{T_{25}} - \frac{1}{T} \right) \right]} \quad \text{T: Thermistor temperature}$$

$$R_{T}: \text{ Thermistor value at T}$$

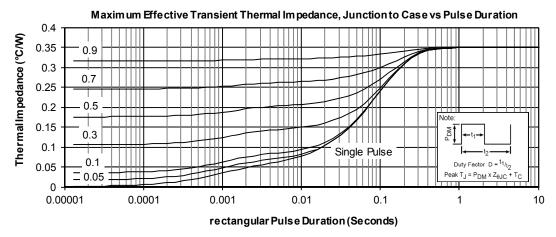
SP4 Package outline (dimensions in mm)

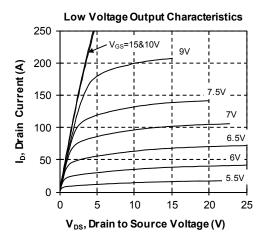


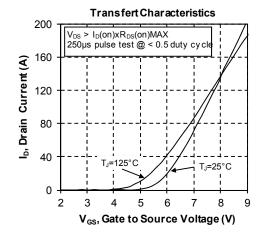
See application note APT0501 - Mounting Instructions for SP4 Power Modules on www.microsemi.com

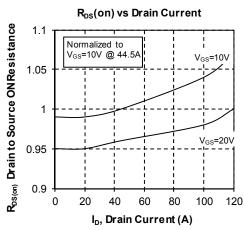


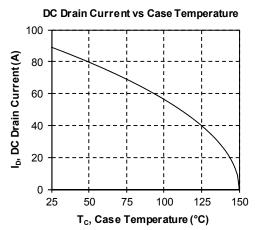
Typical Performance Curve





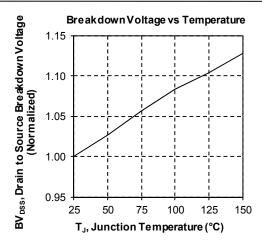


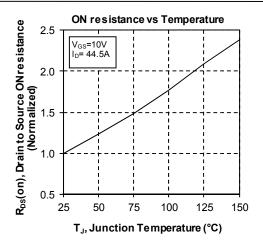


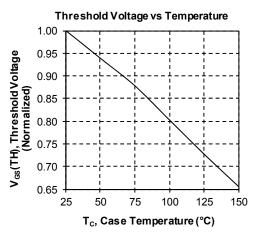


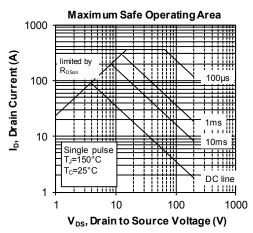
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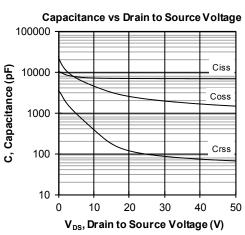


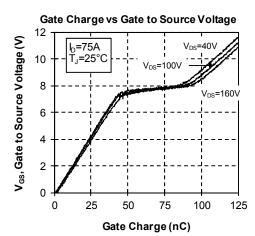




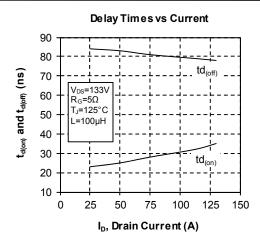


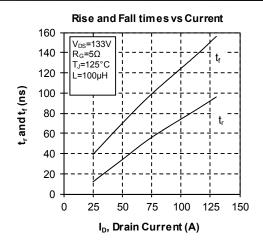


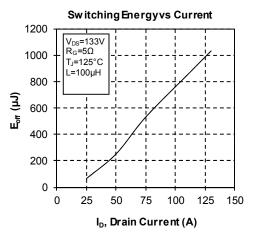


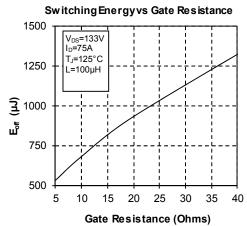


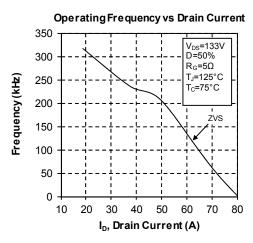


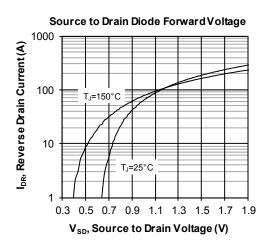














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